

ABSTRACT OF THE INVENTION

A curable composition for use in the fabrication and assembly of circuit components and printed wire boards, which may be designed to be reworkable, comprises one or more mono- or polyfunctional maleimide compounds, or one or more mono- or polyfunctional vinyl compounds other than maleimide compounds, or a combination of maleimide and vinyl compounds, with a free-radical initiator or a photoinitiator, and optionally, one or more fillers. The circuit component is formed by applying the curable composition to the printed wire board and curing the composition *in situ* on the board.

This Sheet Has Been Replaced



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